

Features VS Benefits

- * The GooLED-NIC-7850 Nichia Pin Fin LED Heat Sinks are specifically designed for luminaires using the Nichia LED engines.
- * Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- * For spotlight and downlight designs from 1,200 to 3,500 lumen.
- * Thermal resistance range R_{th} 2.33°C/W.
- * Modular design with mounting holes foreseen for direct mounting of Nichia COB series.
- * Diameter 78.0mm - standard height 50.0mm, Other heights on request.
- * Forged from highly conductive aluminum.



Zhaga LED engine and radiator assembly is a unified future international standardization

- * Below you find an overview of Nichia COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
- * In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.



Nichia LED Modules directly Mounting Options

Nichia COB LED modules name:

- NFCWJ108B;
- NFCLJ108B;
- NFDWJ130B;
- NFDLJ130B;

With the Zhaga Book 3 Holders:

TE LED Holder:2213580-2;

Ideal Holder:50-2103NC;

Direct mounting with machine screws M3x6.5mm, green indicator marks.

- NFCWL036B;
- NFCLL036B;
- NFCWL060B;
- NFCLL060B;

With the Zhaga Book 3 Holders:

Ideal Holder:50-2100NC;

TE LED Holder:2213382-2;

Direct mounting with machine screws M3x6.5mm, Green indicator marks.

With the LEDiL products:

Lena series: CN14xxx; C13xxx; C12xxx;

Ronda series: FN15xxx-xx;

Nichia COB LED modules name:

- NVCWL024Z;
- NVCLL024Z;
- NVNW S007Z;
- NJCWS024Z;

With the Zhaga Book 11 Holders:

BJB holder:47.319.6180.50;

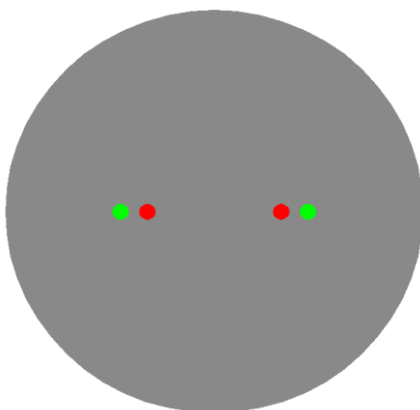
TE LED Holder:2213118-1;

Direct mounting with machine screws M3x8mm, Red indicator marks.

With the LEDiL products:

Lena series: CN14xxx; C13xxx; C12xxx;

Ronda series: FN15xxx-xx;



Mounting Options and Drawings & Dimensions

Example:GooLED-NIC-7850-B-1,2

Example:GooLED-NIC-78 **1** - **2** - **3**

1 Height (mm)

2 Anodising Color

B-Black

C-Clear

Z-Custom

3 Mounting Options - see graphics for details Combinations available

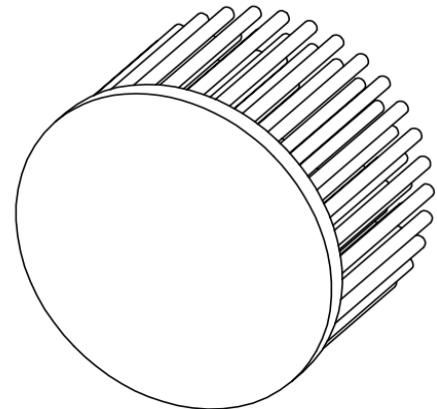
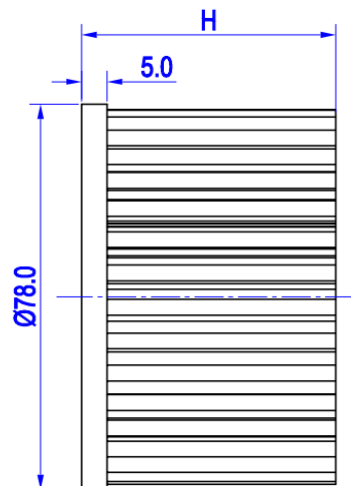
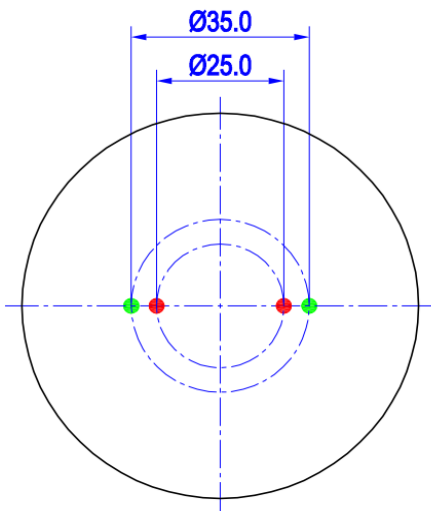
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means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.


MOUNTING OPTION	Module type	Holder NO.	LEDiL products		THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
			Lena series	Ronda series			
N	/	None	None	None	None	None	None
1	NVCWL024Z; NVCLL024Z; NVNWS007Z; NJCWS024Z;	BJB Holder 47.319.6180.50	CN14xxx; C13xxx; C12xxx;	FN15xxx-xx	M3	6.5mm	25.0mm/ 2-@180° (Zhaga book 11)
		TE Holder 2213118-1					
2	NFCWL036B; NFCLL036B; NFCWL060B; NFCLL060B;	Ideal Holder 50-2100NC					
		TE Holder 2213382-2					
	NFCWJ108B; NFCLJ108B; NFDWJ130B; NFDLJ130B;	Ideal Holder 50-2103NC					
		TE Holder 2213358-2					



GooLED

GooLED-NIC-7850 Pin Fin Heat Sink $\Phi 78\text{mm}$ for Nichia

The product data table

	Model No.	GooLED-NIC-7850
	Heatsink Size	$\Phi 78 \times H 50\text{mm}$
	Heatsink Material	AL1070
	Finish	Black Anodized
	Weight (g)	197.0
	Dissipated power ($T_{hs-amb}, 50^\circ\text{C}$)	21.5 (W)
	Cooling surface area (mm^2)	75332
	Thermal Resistance (R_{hs-amb})	2.33 ($^\circ\text{C/W}$)

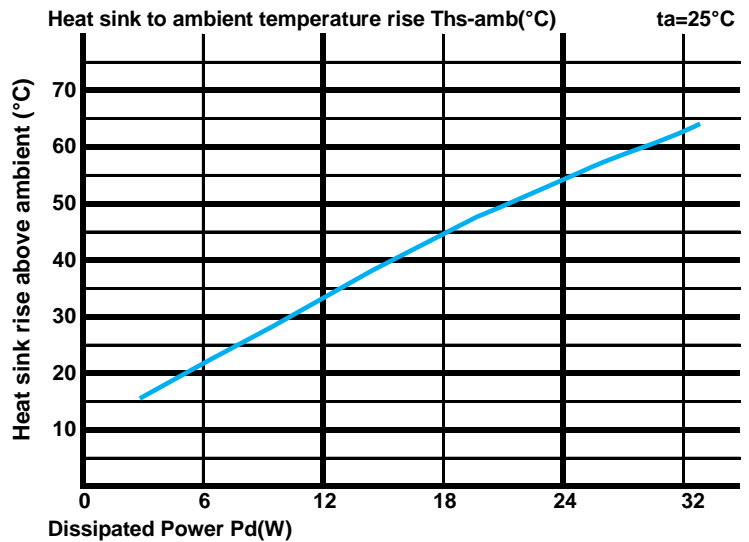
The thermal data table

* Please be aware the dissipated power P_d is not the same as the electrical power P_e of a LED module.

* To calculate the dissipated power please use the following formula: $P_d = P_e \times (1 - \eta_L)$.

P_d - Dissipated power ; P_e - Electrical power ; η_L = Light efficiency of the LED module;

Dissipated Power P_d (W)	$P_d = P_e \times (1 - \eta_L)$	Heat sink to ambient thermal resistance R_{hs-amb} ($^\circ\text{C/W}$)	Heat sink to ambient temperature rise T_{hs-amb} ($^\circ\text{C}$)
		GooLED-NIC-7850	
6.0		3.50	21.0
12.0		2.67	32.0
18.0		2.44	44.0
24.0		2.25	54.0
32.0		1.97	63.0



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (T_{hs} - T_a) / P_d$

θ - Thermal Resistance [$^\circ\text{C/W}$] ; T_{hs} - Heatsink temperature ; T_a - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface (TIM)}$ [$^\circ\text{C/W}$], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ [$^\circ\text{C/W}$], and the ambient temperature is $T_{ambient}$ [$^\circ\text{C}$].

*Thermal resistances outside the package $R_{interface (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point. Thus, the following formula is also used:

$$T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot P_d + T_{ambient}$$